



DEUTSCH

TE Internal #: ZPF000000000000570

Gold (Au), Pin Contact, 20 – 24 AWG, 115 VAC, 115 VDC, .205 – .518 mm² Wire, Spring Contact Retention, Size 20, Discrete Wire, Crimp, Copper Alloy

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Connectors > Contacts > Connector Contacts



Contact Type: **Pin**

Contact Mating Area Plating Material: **Gold (Au)**

Wire Contact Termination Area Plating Material: **Gold**

Operating Voltage: **115 VDC**

Features

Product Type Features

Sealable	Yes
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Configuration Features

Compatible With Wire & Cable Type	Discrete Wire
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Electrical Characteristics

Operating Voltage	115 VDC
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Contact Features

Barrel Type	Closed
Contact Type	Pin
Contact Mating Area Plating Material	Gold (Au)
Wire Contact Termination Area Plating Material	Gold
Contact Retention Within Housing	With
Contact Size	Size 20
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	7.5 A

Termination Features

Termination Method to Wire & Cable	Crimp
Product Terminates To	Wire & Cable

Mechanical Attachment



Contact Retention Type Within Housing

Spring

Dimensions

Wire Size

.205 – .518 mm²

Usage Conditions

Operating Temperature Range

-65 – 125 °C[-85 – 257 °F]

Operation/Application

Circuit Application

Power, Signal & High Speed Data

Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

EU RoHS Directive 2011/65/EU

Compliant with Exemptions

EU ELV Directive 2000/53/EC

Compliant with Exemptions

China RoHS 2 Directive MIIT Order No 32, 2016

Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JUNE 2025 (250)
 Candidate List Declared Against: JAN 2025 (247)
 SVHC > Threshold:
 Pb (1.2% in alloy)

Article Safe Usage Statements:

Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content

Low Halogen - Br, Cl, F < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought

